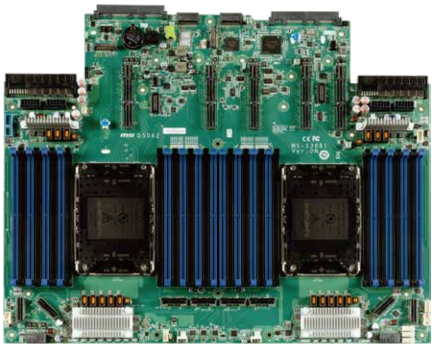
D5062

Intel® Xeon® 6 M-FLW HPM



Dual-Socket Intel® Xeon® 6500/6700 DC-MHS M-FLW HPM

The dual-socket Intel® Xeon® 6500/6700 series server platform is optimized for maximum memory capacity and high-TDP processors. With a clear separation between host processors and management/control logic, the DC-MHS form factor enables customers to standardize BMC and security functions across diverse CPU types and vendors within their fleet.

SPECIFICATIONS

Dimensions (Width x Height)
423mm x 348mm

Processor
Dual Intel® Xeon® 6700E-series, 6500P-series and 6700P-series processors, TDP up to 350W

Memory
(32) DDR5 DIMM slots, 8 channels per CPU (2DPC), RDIMM/RDIMM-3DS/MRDIMM
- Max. Frequency:
  RDIMM: 6400MT/s (1DPC), 5200MT/s (2DPC)
  MRDIMM: 8000MT/s (only support 1DPC)
- Max. Capacity per DIMM: 256GB (RDIMM), 64GB (MRDIMM)

* MRDIMMs are only supported with Intel® Xeon® 6 P-core series processors

Expansion Slots
(5) PCIe 5.0 x16 SFF-TA-1033 MXIO slots (2 from CPU0, 3 from CPU1)
(8) Far-Side PCIe5.0 x8 MCIO 8i connectors (4 from CPU0, 4 from CPU1)

Networking
(1) PCIe 5.0 x16 OCP3 NIC mezzanine slot (CPU0, NCSI supported)

Storage
(2) 2280/22110 PCIe 5.0 x2 NVMe M.2 ports (CPU0)
(2) E1.S 9.5mm PCIe 5.0 x4 ports (CPU1)

RAID
NVMe RAID 0/1/5/10 support
(Intel® VROC RAID key required)

Server Management
Support via DC-SCM module MGT1:
(1) 1000Base-T Dedicated Server Management port
ASPEED AST2600 with AMI MegaRAC based firmware supporting IPMI 2.0 and DMTF Redfish API
Dual BIOS and dual BMC
eMMC for local BMC storage media

Security
Chassis intrusion (header on board)
Support via DC-SCM module MGT1:
- TPM2.0 module (optional)
- ASPEED AST1060 Hardware Root of Trust module (optional)

USB
(1) 20pin-header for 2 ports USB3.0

Rear I/O
Support via DC-SCM module MGT1

Internal I/O
(1) Edge slot for DC SCM2.0 module (MGT1)
(1) Buzzer
(1) Chassis intrusion header
(4) I2C headers
(1) 20pin-header for 2x USB3.0
(2) DC MHS Control Panel Header for the front panel (one left one right)
(1) 4-pin header for liquid cooler leaking sensor
(2) 4-pin FAN headers

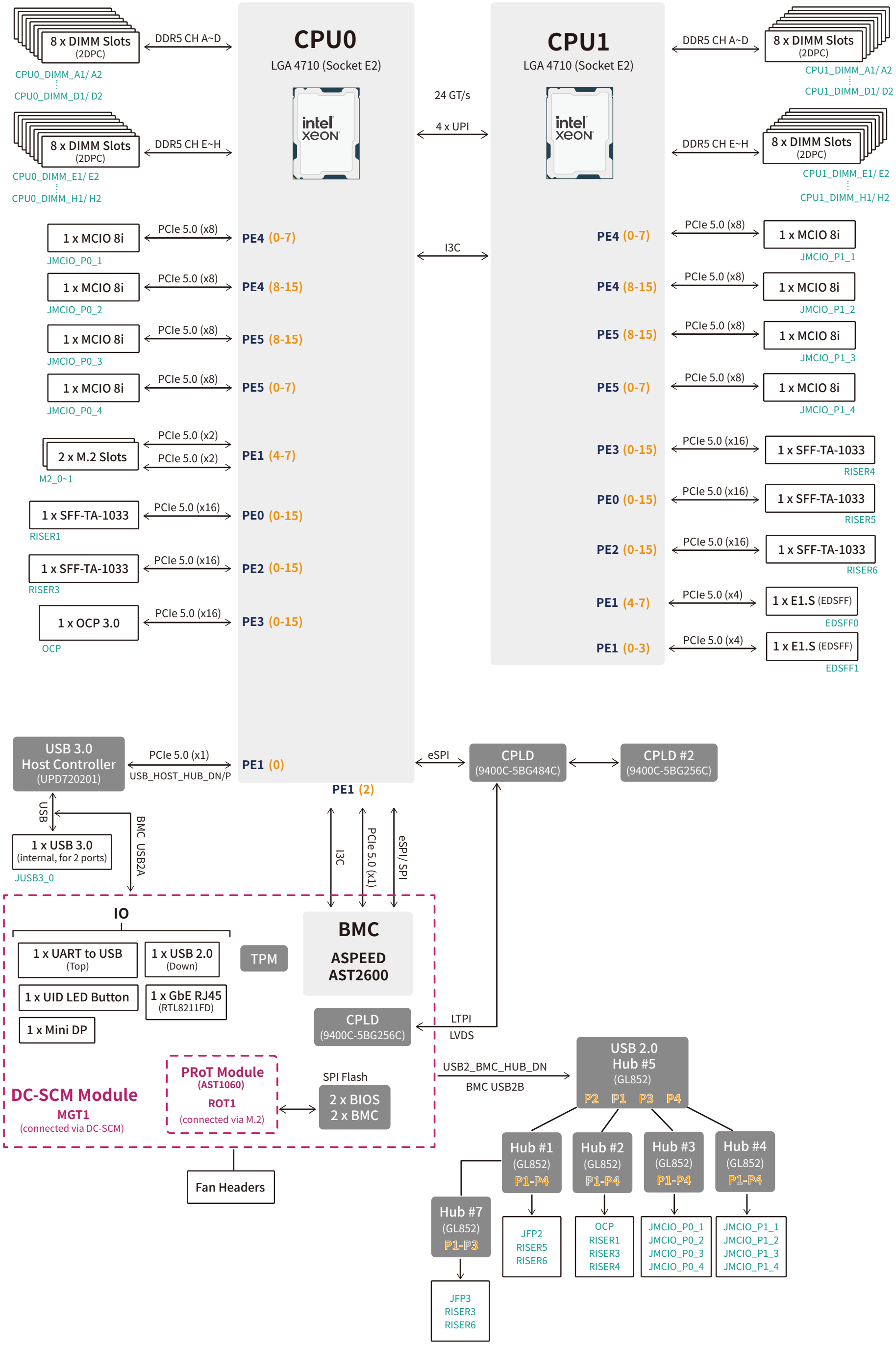
Power Connector
(2) CRPS/M-CRPS 73.5 power connectors
(6) 12-pin PICPWR connectors

Environmental
System Operating Temperature: 0°C ~ 35°C
Non-operating Temperature: -20°C ~ 70°C
Non-operating Relative Humidity: 5% ~ 85% (non-condensing)

Regulatory
FCC (Class A), CE

Version D:04302025

D5062 HPM Block Diagram



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